

## **20-3290**

# **POTTING, ENCAPSULATING & CASTING EPOXY RESIN**

### **DESCRIPTION:**

20-3290 is a high temperature two part epoxy system. This system has low thermal coefficient of expansion, good thermal shock resistance and high temperature service. 20-3290 is used in a wide variety of electronic potting and encapsulating applications.

### **TYPICAL SPECIFICATIONS:**

Mixed viscosity @ 25°C, cps	24,000
Specific gravity, 25°C	1.39
Color	Natural
Hardness, shore D	75
Water Absorption, 24 hrs, 25°C	0.2
Dielectric strength volts/Mil	400
Dielectric constant at 60 Hz	4.0
Dissipation factor at 60 Hz	.02
Volume resistivity, ohm-cm	$5 \times 10^3$

### **INSTRUCTIONS FOR USE:**

1. Resin and Catalyst may be pre-heated to 80°C before mixing to reduce the viscosity.
2. By weight thoroughly mix two parts 20-3290R Epoxy Resin to three parts 20-3290C Curing Agent.
3. Pour and cure for 4 hours @ 90-100°C.

### **IMPORTANT:**

The information in this brochure is based on data obtained by our research and is considered accurate. However, no warranty is expressed or implied regarding the accuracy of these data, the results to be obtained from the use thereof, or that any such use will not infringe any patent. This information is furnished upon the condition that the person receiving it shall make his own tests to determine the suitability thereof for his particular purpose.

06/06